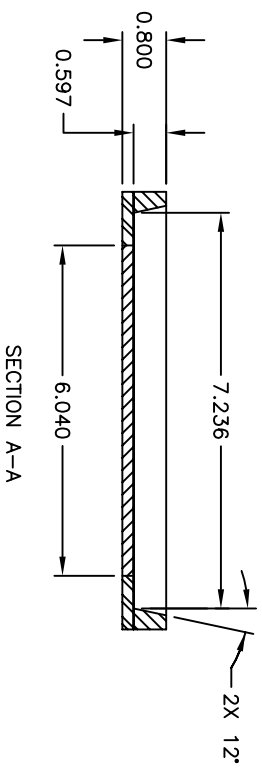
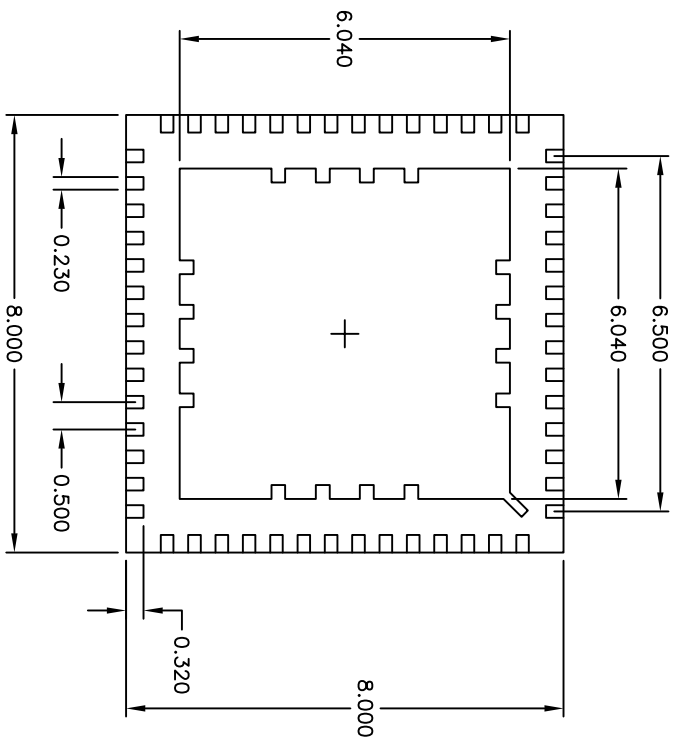
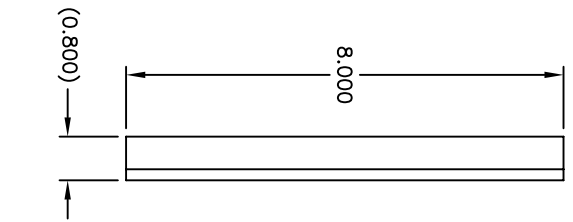
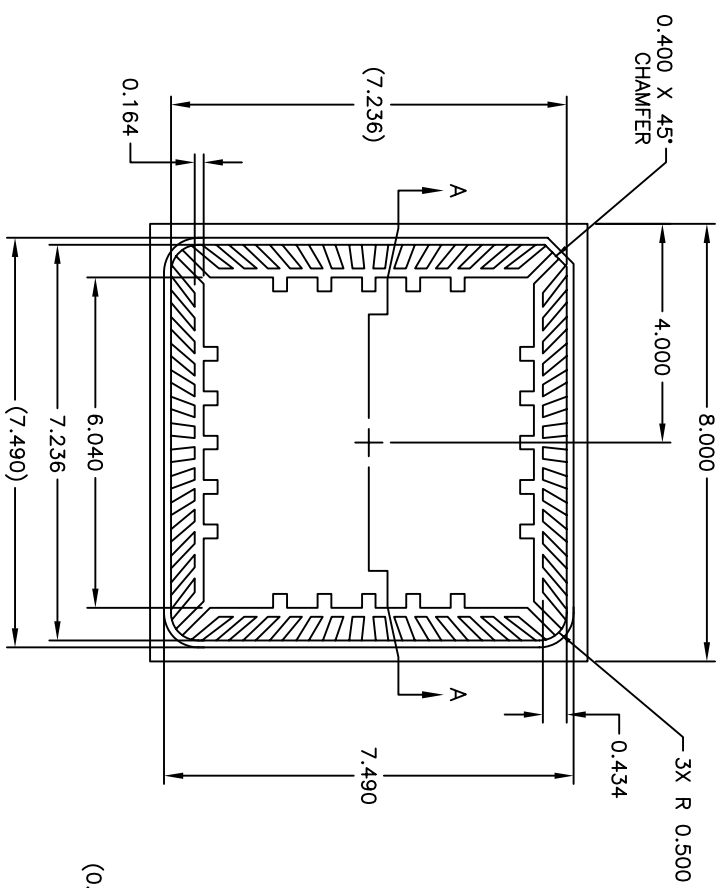


REVISIONS			APPROVED
EON NO.	DATE	DESCRIPTION	D.BENAVANDO
10503	10/27/05	PRODUCTION RELEASE	



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
  2. LEAD FRAME: COPPER, 194 FH.
  3. LEAD FINISH: FULL GOLD PLATE.
  4. FRAME THICKNESS: 0.2030 ±.0076.
  5. DIE PAD: 6.040 X 6.040.
  6. JEDEC OUTLINE: MO-220 (VLLD-5).

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS  
TOLERANCES ARE: X.XXX ± 0.15 X.XXXX ± 0.010 ANGLES: ± 1°

THIRD ANGLE PROJECTION

DO NOT SCALE DRAWING

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DRAWN BY	W. GRIFFITTS	DATE	10/26/05
APP BY	P. FLASKERUD	DATE	10/26/05

**SEMPAC, INC.**  
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SUNNYVALE, CALIFORNIA 94089  
PHONE: (408) 400-9002 FAX: (408) 400-9006

56 Lead 8mm x 8mm  
MLP Open-Pak

SIZE	PART NO.	REV
A	MLP8X8-56-OP-01	3

SCALE NONE FILE MLP8X8-56-OP-01-R3.DWG SHEET 1 OF 1